



Product Specification

Product:	Conductive Platinum Paste, Co-Fired Platinum Paste
Part Number:	55H-1803

Application Scope :

This product is suitable for high-temperature co-fired electrodes and sensor products.

Usage Conditions :

Substrate	High temperature ceramic
Printing	200-300 mesh screen printing
Leveling	It will level at room temperature for 5-15 minutes (depending on the actual leveling situation).
Drying	Bake in an oven at 100-150°C for 10-15 minutes (if the temperature is below 300°C, adjust the baking time according to actual conditions)
Firing Condition	Sintering in a tunnel furnace under air atmosphere at a peak temperature of 850~1300°C (recommended value) for at least 10 minutes. The minimum firing temperature can be as low as 800°C, and the maximum temperature resistance can reach 1500°C
Thinner	ST-1000

Characteristics :

1. Paste Characteristics :

Characteristic	Standard	Test Method And Conditions
1 Fineness	$\leq 5\mu\text{m}$	FOG test
2 Viscosity	120-280Pa.s	Brookfield HBT (Boli Fei) viscometer, rotor model SC4-14/6R, operates at 10rpm with viscosity adjustable within $25\pm 1^\circ\text{C}$ according to user requirements.

2. Characteristics After Curing :

Under sintering conditions 1, the film thickness ranges from 8 to 12 microns.

Check fired film produced under the conditions specified in 1) , (Film thickness is $8-12\mu\text{m}$.)



Characteristics		Standard	Test Method And Conditions
3	Resistivity	$\leq 50\text{m}\Omega/\square$	Test pattern 0.6mm×60mm
4	Adhesion		Peel Test: 0.5mm \varnothing Tin plated Cu wire soldered on 2mm×2mm Pad. Solder: 96.5Sn/0.5Cu Mildly activated flux used.
	Initial Adhesion	$\geq 45.2\text{N}$	
	Aging Adhesion	$\geq 24.6\text{N}$	Aging conditions: 150°C, 24 hours

Save Conditions And Validity Period :

The product should be stored in a sealed environment at 5-25°C. The shelf life is 1 year from the date of shipment.

Packaging Method :

Standard packaging: 1000g per can. Samples are available in 200g small cans.